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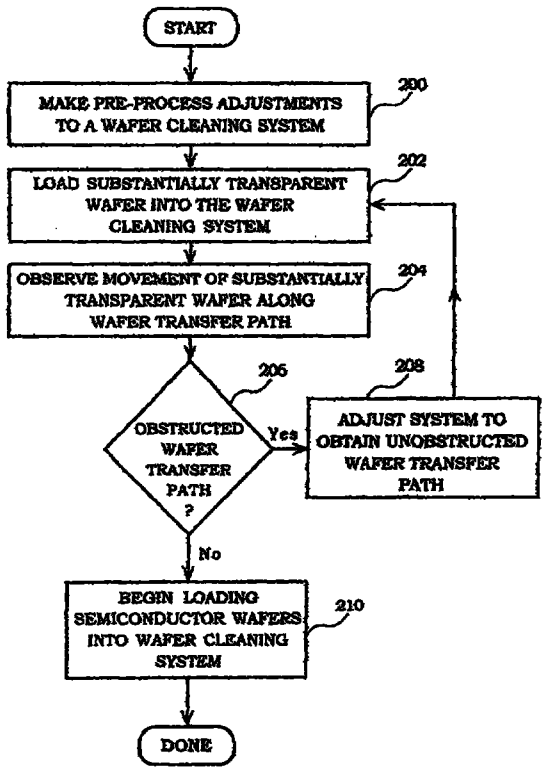
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(54) Title: METHOD FOR VALIDATING PRE-PROCESS ADJUSTMENTS TO A WAFER CLEANING SYSTEM



(57) Abstract: A method for validating pre-process adjustments to a wafer cleaning system includes the operations of: (a) making pre-process adjustments to a wafer cleaning system (200), (b) loading a substantially transparent wafer into the wafer cleaning system (202), and (c) observing the substantially transparent wafer as the substantially transparent wafer moves along a wafer transfer path in the wafer cleaning system (204). In the event undesirable contact between the substantially transparent wafer and components of the wafer cleaning system is observed (206), the method further includes (d) making adjustments to the wafer cleaning system formulated to avoid undesirable contact between semiconductor wafers to be processed and components of the wafer cleaning system (208), and (e) repeating operations (b) through (d) until the substantially transparent wafer moves along the wafer transfer path without undesirable contact with components of the wafer cleaning system. The method also may include observing the substantially transparent wafer to confirm that liquid sprayed from below the wafer during rinsing operations properly contacts the bottom side of the wafer.

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